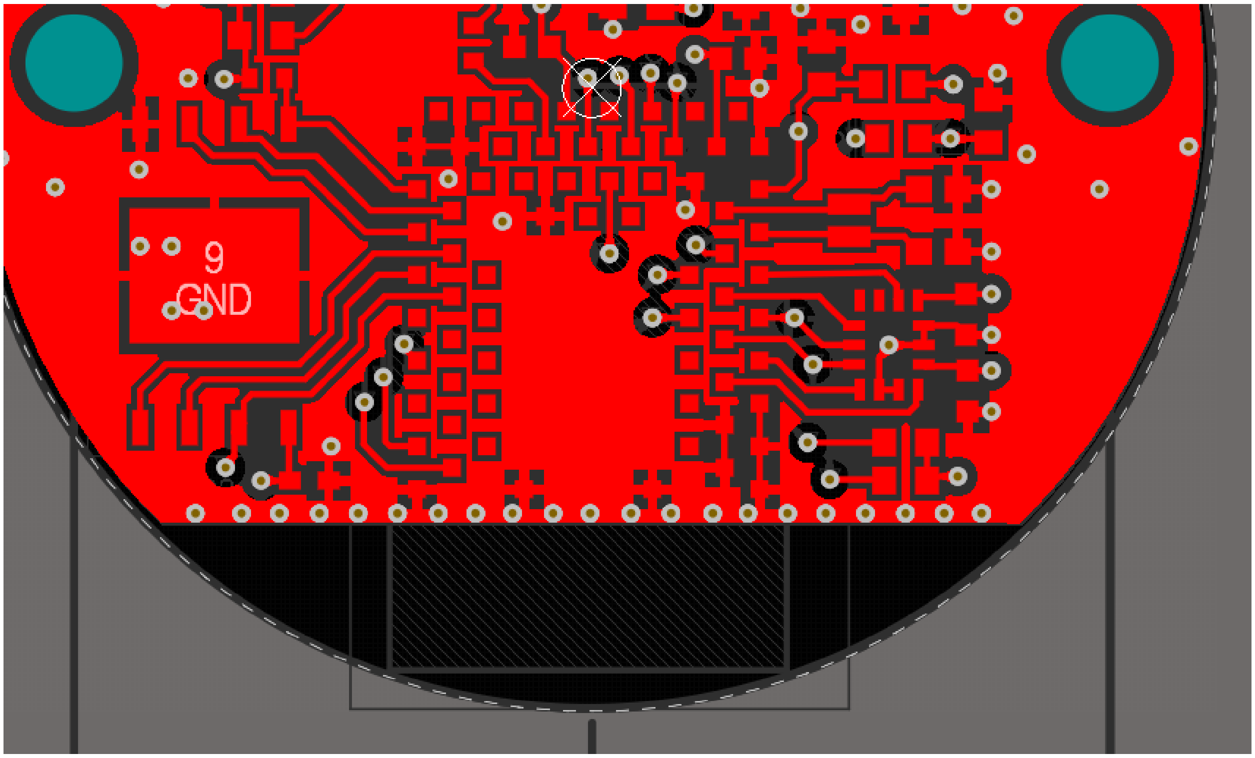
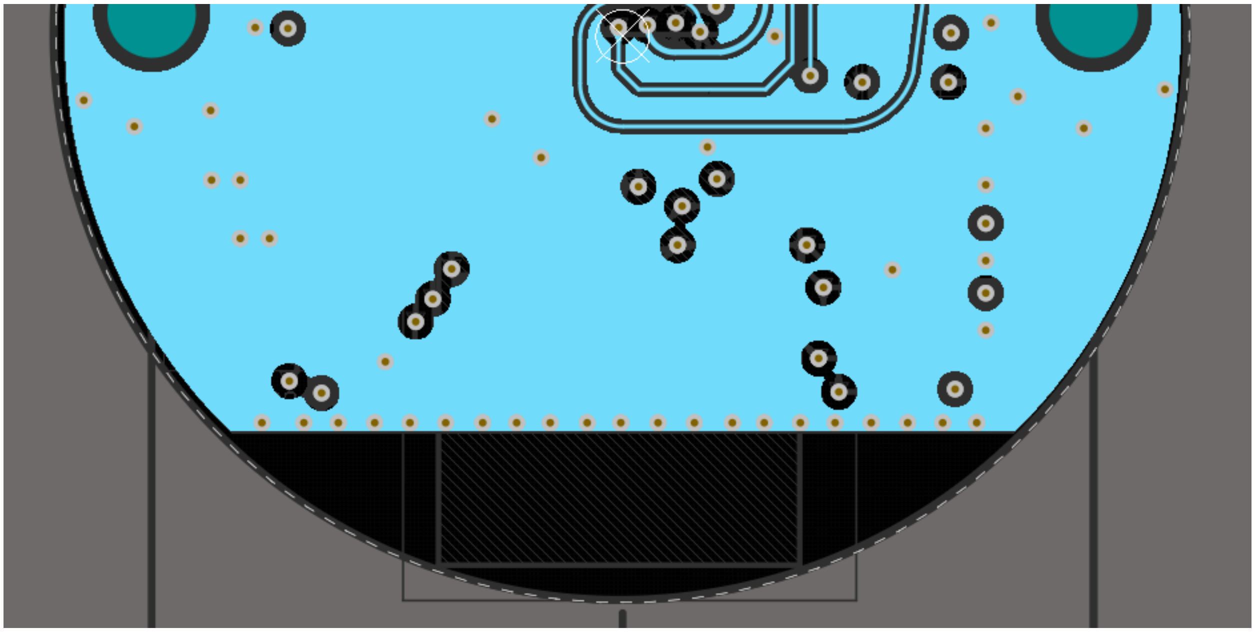
Layer-1 (Top Layer- BMD placed- BGA package)

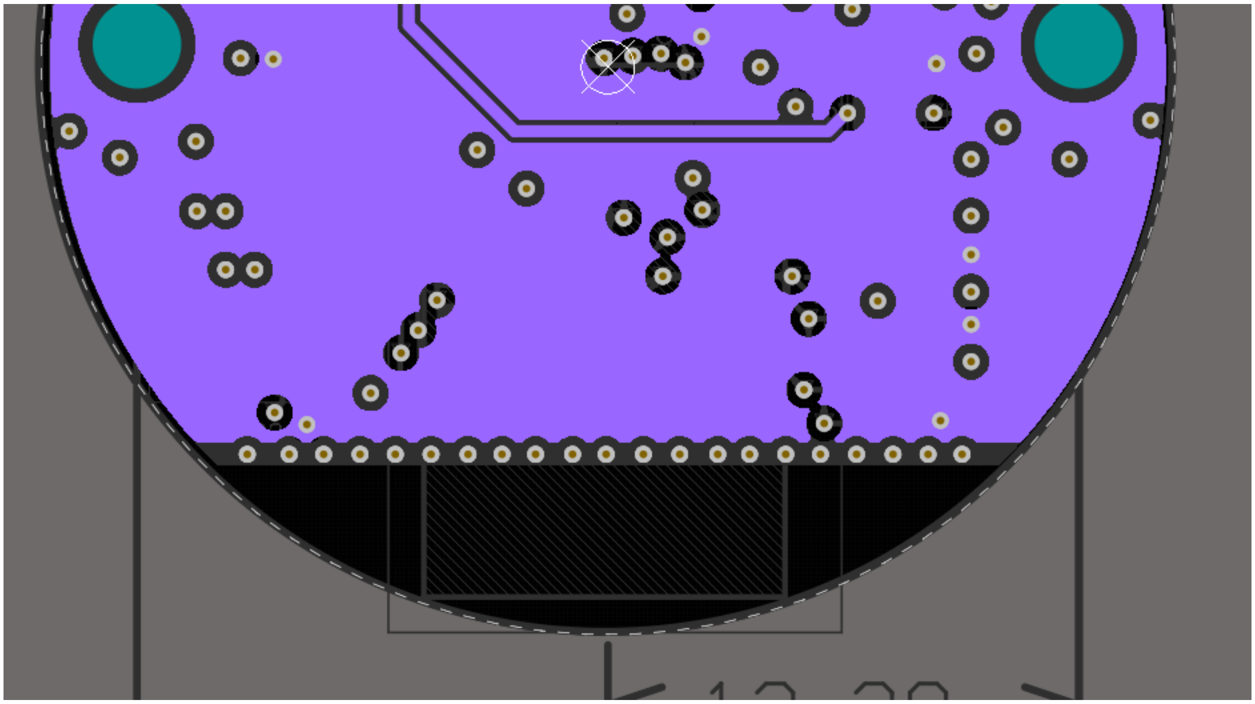


- No impedance match
- No copper on beneath the chip antenna
- 10/20 mil mechanical via.
- 4 layer stack up
- Core material- TU-768

Layer-2



Layer-3



Layer-4(Bottom layer)